

High-Grade

DATA CONVERTER FOR THE APPLE II

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Part 2: Checkout, calibration, and use

LAST month, we discussed the principles of A/D and D/A conversion and described a converter for the Apple II. Here are the software and instructions needed to operate the converter.

Checkout & Calibration. Plug one end of a ribbon cable with DIP headers on each end into Port A at *SO4* on the interface adapter. Then, making sure the Apple computer is powered down, install the VIA in slot 5 of the computer. Plug the other end of the cable into a solderless-socket breadboard and use wire jumpers to connect D0 through D7

to ground at pin 11. Switch on the computer and wait for the prompt to appear on-screen. Measure the voltages at pins 50, 33, and 25 of the computer's bus connector; they should read +12, -12, and +5 V, respectively.

For the following discussion, the interface is assumed to be plugged into slot 5 of the computer and all data lines are grounded.

Enter and run Program 1 to test the input to Port A. Displayed on-screen should be a running column of 0s read in from Port A. One at a time, remove the data line jumpers from ground and note the change in status dis-

played on-screen. As each data line is ungrounded, it should display a 1 on the screen. If it doesn't, the interface adapter most likely isn't plugged into slot 5 of the computer and/or the program hasn't been correctly entered. If the problem still persists after making sure that the adapter is in slot 5 and the program has been properly entered, use a dual-trace oscilloscope to check the *IC7* delay circuit. For proper operation, the signal observed at pin 6 of *IC7* should be delayed by about 180 ns with respect to the signal at pin 1.

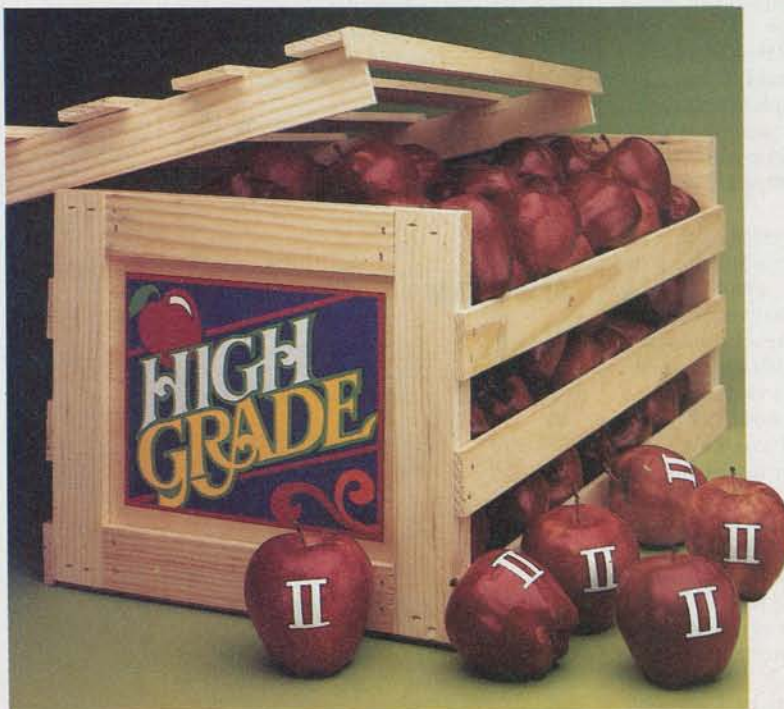
Remove the ground connections

from D0 through D7 and load and run Program 2 to test the output. For Byte=0, there should be no voltage (0 volt) between each data line and ground; for Byte=255, each data line should be at +5 volts; for Byte=55, D0 through D7 should be 10101010, etc.

Load and run Program 3 to test control line CA2. Making measurements at *J6*, CA2 should be 0 V for PC=12 and +5 V for PC=14.

To test Port B, power down the computer and move the DIP cable to *SO3*. Repeat the above three tests, changing the POKE and PEEK addresses for DDRB and ORB as detailed in Table I. The PCR address doesn't change, but the values for PC change to 192 for 0 V and 224 for +5 V to operate CB2.

Having ascertained proper port and control operation, remove the ICs from the Data Converter assembly, power down the computer, and plug the 16-pin DIP cable into *SO3*, the Port B connector. Power up the computer and confirm that +12, -12, and +5 V are present at the appropriate IC socket pins. (Bear in mind that under these no-load conditions some non-power pins will measure high.) Having con-



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firmed that the proper voltages are present at the appropriate pins, power down the computer, insert the ICs in their respective sockets (take care to observe proper orientation), and power up once again.

Connect a voltmeter to *J2* and ground the center connector of *J1* to begin testing the analog amplifier. Set the project's GAIN switch to 1 and adjust trimmer *R3* for a 0-V output. Set the GAIN switch to 500 and adjust *R3* for minimum positive output. To check calibration of the GAIN control, remove the short from across *J1* and replace it with a 10,000-ohm potentiometer connected across a D cell (use the wiper and one end lug of the pot to make connections to the converter circuit) to provide the dc signal input. Make up a table of input vs output for each of the six positions of the GAIN switch for use in making software corrections to compensate for nonlinearities in gain.

If you have access to an audio oscillator and an oscilloscope, feed sine waves into *J1* and monitor *J2* to observe that the amplifier has reasonably flat response from dc to 15 kHz.

Enter and run Program 4 to check D/A conversion. A voltmeter connected between DAC *J5* and ground should indicate 0 V when DB is 0 and 2.55 V when DB is 255.

Use Program 5 to generate a square wave whose pitch is controlled by the value of P for checking the audio amplifier. This square-wave signal can be observed at *J5* with a scope.

Program 6 sets DDRB=0 for all inputs for testing the digital I/O lines. D1 through D6 will float high while D0 and D7 are checked. The running display produced by this program will change according to whether D0 or D7 is shorted (see Table II).

A/D conversion is tested with Program 7. This simple diagnostic program is written in BASIC, which is slow enough to complete a conversion before being read. Results are continuously displayed on-screen. With *J1* grounded and the GAIN switch set to 1, the reading should be 0 on dc and about 127 on ac. Connect the pot/D-cell assembly to *J1* and slowly vary the setting of the pot (dc input level). The on-screen display should follow the changes. Make sure the -9-volt reference is present at pin 2 of *IC2*. A scope connected to TRIG *J6* should reveal CB2 going high for about one-third or one-quarter of the pulse cycle. Without this pulse, no A/D conversion is possible.

Set AC/DC switch *S2* to DC for ampli-

PROGRAM 1

```
100 REM PROGRAM #1
120 REM PORT A INPUT TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM SET PORT A DDRA
FOR INPUT
170 D=0
180 POKE 49363,D
190 :
200 REM READ ORA WHILE
CHANGING
210 REM JUMPERS FROM D0-D7
TO GROUND
220 PRINT PEEK (49375)
230 :
240 FOR PAUSE = 1 TO 200: NEXT
250 GOTO 220
```

PROGRAM 2

```
100 REM PROGRAM #2
120 REM PORT A OUTPUT TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM SET PORT A DDRA
FOR OUTPUT
170 D=255
180 POKE 49363,D
190 :
200 INPUT "BYTE"; B
210 REM OUTPUT BYTE TO
PORT A
220 REM TEST DO-D7 WITH
VOLTMETER
230 POKE 49375, B
240 GOTO 200
```

PROGRAM 3

```
100 REM PROGRAM #3
120 REM PORT A CONTROL
125 REM LINE CA2 TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM CA2 GOES LOW ON 12
170 REM AND HIGH ON 14
180 :
190 INPUT "PCR BYTE=?"; PB
200 POKE 49372, PB
210 GOTO 190
```

PROGRAM 4

```
100 REM PROGRAM #4
120 REM DAC TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM SET DDRB FOR OUT
170 POKE 49362,255
180 :
190 REM SET CB2 HIGH SO DAC
200 REM CHIP ENABLE IS LOW
210 POKE 49372,224
220 :
230 REM OUTPUT DB TO DAC
AR ORB
240 INPUT "DAC BYTE=?";DB
250 POKE 49360,DB
260 GOTO 240
```

PROGRAM 5

```
100 REM PROGRAM #5
120 REM AUDIO AMP TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM SET DDRB FOR OUTPUT
170 POKE 49362,255
180 :
190 REM SET CB2 HIGH SO DAC
200 REM CHIP ENABLE IS LOW
210 POKE 49372,224
220 :
230 INPUT "PAUSE BYTE=?";P
240 POKE 49360,0: GOSUB 290
250 POKE 49360,255: GOSUB 290
260 GOTO 240
270 END
290 FOR PAUSE = 0 TO P:
NEXT: RETURN
```

PROGRAM 6

```
100 REM PROGRAM #6
120 REM DIGITAL I/O TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM SET DDRB FOR INPUT
170 POKE 49362,0
180 :
190 REM GROUND D0 OR D7
(4 WAYS)
200 PRINT PEEK (49360)
210 GOTO 200
```

PROGRAM 7

```
100 REM PROGRAM #7
120 REM ADC TEST
130 REM 6522 VIA IN SLOT 5
150 :
160 REM SET DDRB FOR INPUT
170 POKE 49362,0
180 :
190 REM MAKE READ HIGH
(WITH CB2)
200 REM AND START
CONVERSION
210 POKE 49372,224
220 :
230 REM MAKE READ LOW
(WITH CB2)
240 REM PREPARE TO READ
CONVERSION
250 POKE 49372,192
260 :
270 REM READ ADC
280 PRINT PEEK (49360)
290 :
300 GOTO 210
```

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tude calibration. Apply the full potential from the D cell to J1. Assume this to be 1.46 V, the voltmeter will indicate 7.01 V with the GAIN switch set to 5. This means that gain is actually 4.80

TABLE I—6522 VIA ADDRESSES, SLOT 5

Starting address	49360 (\$CODO)
DDRA	49363
ORA	49375
DDRB	49362
ORB	49360
PCR	49372
ACR	49371

TABLE II—DIGITAL I/O TEST

D7	D6	D5	D4	D3	D2	D1	D0	Screen
0	1	1	1	1	1	1	0	126
0	1	1	1	1	1	1	1	127
1	1	1	1	1	1	1	0	254
1	1	1	1	1	1	1	1	255

(7.01/1.46), although the A/D converter actually "sees" 7.01 V. Measure reference voltage V_{REF} between J3 and ground. Assume it to be 8.56 volts. With full scale for the converter being 255 for any V_{REF} , the A/D converter will produce 209 (7.01/8.56). Working backward, we find that $V_{INPUT} = (A/D \text{ output/gain}) \times (V_{REF}/255)$. This means that conversion accuracy depends on voltmeter accuracy. Often, true V_{INPUT} isn't needed, since relative amplitude will be sufficient.

Frequency accuracy requires use of a frequency counter to set a square-wave generator to 1000 Hz (the actual frequency isn't important as long as it is known). Feed the square waves into J1 and use Table III to run the A/D converter fast enough to digitize the waveform. The Apple monitor program can be used to "look at" the bytes in memory. Another way to do this is to use a short BASIC program written to PEEK the bytes onto the screen. In either case, count the number of bytes per complete

cycle of the square wave and multiply by the frequency to obtain A/D conversion sampling rate. If the A/D timing bytes are changed, this frequency calibration can be performed and recorded for a range of digitizing rates.

Operation Under Assembly Language. For A/D or D/A at rates of less than 50 samples per second, such BASIC programs as those in Programs 1 through 7 are adequate. To realize rates up to 17,000 samples per second for A/D and output rates to 33,000 bytes per second with D/A, both converters must be operated with assembly-language programs. Table III is for A/D, while Table IV is for D/A code.

Operation of Table III code is similar to operation of Program 7. Port A DDRA is set for input with the A/D converter getting a high on its Read line via CA2 to initiate conversion. A loop of at least 20 μ s allows the A/D section to convert the input signal. When the Read line goes low, via CA2, conversion

TABLE III—ADC ASSEMBLY LANGUAGE

\$9300	A9 00	START	LDA	\$00	
02	A8		TAY		INITIALIZE Y
03	85 FE		STA	MEM	SET START OF DATA STORAGE—
05	A9 88		LDA	\$88	ALTER FROM BASIC
07	85 FF		STA	MEM+	
09	A9 00		LDA	\$00	MAKE PORT A ALL INPUTS
0B	8D D3 C0		STA	DDRA	
0E	78 EA EA		SEI		
11	A9 0E	ADC	LDA	\$0E	MAKE READ HIGH, START CONVERSION
13	8D DC C0		STA	PCR	
16	A2 05		LDX	\$05	GIVE ADC > 20 MICROSECONDS
18	CA	WAIT1	DEX		TO CONVERT
19	D0 FD		BNE	WAIT1	
1B	A9 0C		LDA	\$0C	MAKE READ LOW, PREPARE TO
1D	8D DC C0		STA	PCR	READ ADC
20	AD DF C0		LDA	ORA	READ ADC
23	91 FE		STA	(MEM), Y	STORE DATA
25	20 40 93		JSR	MSEC	DELAY BETWEEN SAMPLES
28	C8		INY		
29	D0 E6		BNE	ADC	
2B	E6 FF		INC	MEM+	PREPARE TO FILL NEXT MEMORY PAGE
2D	A6 FF		LDX	MEM+	WITH DATA
2F	E0 92		CPX	\$92	CHECK FOR END OF MEMORY
31	D0 DD		BNE	ADC	
33	58		CLI		
\$9334	60		RTS		
\$9340	A9 00	MSEC	LDA	\$00	SET VIA TIMER 2 FOR ONE-SHOT
42	8D DB C0		STA	ACR	TIME INTERVAL
45	A9 E8		LDA	\$E8	\$03E8 GIVES ABOUT 1 msec
47	8D D8 C0		STA	T2L	INTERVAL—POKE CHANGES
4A	A9 03		LDA	\$03	FROM BASIC
4C	8D D9 C0		STA	T2H	
4F	A9 20		LDA	\$20	TIMER 2 INTERRUPT FLAG MASK
51	2C DD C0	WAIT2	BIT	IFR	IS FLAG SET?
54	F0 FB		BEQ	WAIT2	IF NOT, THEN LOOP
56	AD D8 C0		LDA	T2L	TIMED OUT—CLEAR FLAG
\$9359	60		RTS		

TABLE IV—DAC ASSEMBLY LANGUAGE

\$9200	A9 FF		LDA	\$FF	SET UP PORT A FOR OUTPUT
02	8D D3 C0		STA	DDRA	TO DAC
05	A5 FE		LDA	FE	SAVE CONTENTS OF TWO ZERO PAGE
07	48		PHA		ADDRESSES USED FOR MEM AND MEM+
08	A5 FF		LDA	FF	IN (IND), Y ADDRESSING
0A	48		PHA		
0B	EA		NOP		
0C	A9 00	START	LDA	\$00	INITIALIZE Y FOR (IND), Y MEMORY SCAN
0E	A8		TAY		
0F	85 FE		STA	MEM	START DATA READOUT AT \$8800
11	A9 88		LDA	\$88	
13	85 FF		STA	MEM+	
15	EA		NOP		
16	78		SEI		MAKE DAC OUTPUT GLITCHLESS
17	A9 0C		LDA	\$0C	MAKE CA2 LOW TO TURN OFF DAC
19	8D DC C0		STA	PCR	
1C	A9 0E		LDA	\$0E	MAKE CA2 HIGH TO TRIGGER SCOPE
1E	8D DC C0		STA	PCR	AND ENABLE DAC
21	EA		NOP		

NOTE: CA2 GETS INVERTED BEFORE IT GETS TO DAC, BY 7416 HEX INVERTER

22	B1 FE	DAC	LDY	(MEM),Y	DISPLAY MEMORY CONTENTS
24	8D DF C0		STA	ORA	ON SCOPE
27	20 50 92		JSR	DELAY	
2A	C8		INY		DAC GETS ONE PAGE AT A TIME
2B	D0 F5		BNE	DAC	
2D	E6 FF		INC	MEM+	MOVE TO NEXT PAGE
2F	A6 FF		LDX	MEM+	TO CHECK FOR TOP LIMIT
31	E0 92		CPX	\$92	
33	D0 ED		BNE	DAC	
35	EA		NOP		
36	58		CLI		
37	C6 FD		DEC	NSCAN	HAVE N SCANS BEEN COMPLETED?
39	A5 FD		LDA	NSCAN	
3B	D0 CF		BNE	START	
3D	EA		NOP		
3E	68		PLA		
3F	85 FF		STA	FF	REPLACE ZERO PAGE CONTENTS
41	68		PLA		
42	85 FE		STA	FE	
\$9244	60		RTS		
\$9250	A2 02	DELAY	LDX	\$N	DELAY BYTE
52	CA		DEX		
53	D0 FD		BNE		
55	60		RTS		

TABLE V—CLEAR MEMORY ASSEMBLY LANGUAGE

\$9280	A0 00		LDY	\$00	INITIALIZE Y FOR (MEM),Y
82	A5 FE		LDA	FE	SAVE CONTENTS OF TWO ZERO PAGE
84	48		PHA		MEMORY LOCATIONS USED FOR
85	A5 FF		LDA	FF	(IND), Y ADDRESSING OF
87	48		PHA		MEM AND MEM+
88	A9 88		LDA	\$88	START CLEARED AREA AT PAGE \$88
8A	85 FF		STA	MEM+	
8C	A9 00		LDA	\$00	
8E	85 FE		STA	MEM	
90	A9 00		LDA	\$00	BYTE TO FILL MEMORY
92	91 FE	CLEAR	STA	(MEM),Y	
94	C8		INY		FILL MEMORY
95	D0 FB		BNE	CLEAR	
97	E6 FF		INC	MEM+	
99	A6 FF		LDX	MEM+	
9B	E0 92		CPX	\$92	
9D	D0 F3		BNE	CLEAR	
9F	68		PLA		REPLACE ZERO PAGE CONTENTS
A0	85 FF		STA	FF	
A2	68		PLA		
A3	85 FE		STA	FE	
A5	60		RTS		

TABLE VI—APPLE ADC LOCATIONS (SLOT 5 ASSUMED)

Hex	Address		Explanation
	Hex	Decimal	
\$9300	37632		Start of ADC Assembly language program
9306	37638		Set beginning of data storage pages \$88-\$91 (136-145)
930C	37644		DDRA LOW \$D3 (211) DDRB LOW \$D2 (210)
930D	37645		DDRA high \$C0 (192) DDRB HIGH \$C0 (192)
9312	37650		READ HIGH (CA2 OR CB2) START CONVERSION*
931C	37660		READ LOW PREPARE TO READ CONVERSION*
9321	37665		ORA LOW \$DF (223) ORB LOW \$D0 (208)
9322	37666		ORA HIGH \$C0 (192) ORB HIGH \$C0 (192)
9330	37680		SET END OF DATA STORAGE MEMORY
9346	37702		T2L BYTE
934B	37707		T2H BYTE
9359	37721		LAST OP CODE (90 BYTES)
CA2	low \$0C 12	high \$0E 14	
CB2	\$C0 192	\$E0 224	

TABLE VII—APPLE DAC LOCATIONS (SLOT 5 ASSUMED)

Hex	Address		Explanation
	Hex	Decimal	
\$9200	37376		BEGINNING
9203	37379		DDRA LOW BYTE (211) DDRB LOW BYTE (210)
9204	37380		DDRA HIGH BYTE (192) DDRB HIGH BYTE (192)
9212	37394		SET BEGINNING OF SCAN-PAGE 136 TO 145
9218	37400		SET CA2 LOW (12) SET CB2 LOW (192)
921D	37405		SET CA2 HIGH (14) SET CB2 HIGH (224)
9225	37413		ORA LOW BYTE (223) ORB LOW BYTE (208)
9226	37414		ORA HIGH BYTE (192) ORB HIGH BYTE (192)
9232	37426		SET END OF SCAN (SCAN UP TO THIS PAGE)
9251	37457		SCAN DELAY BYTE (0 TO 225)
9257	37463		LAST OP CODE
00FD	253		NUMBER OF SCANS BEFORE RETURN KEY IS CHECKED

TABLE VIII—CLEAR MEMORY LOCATIONS (SLOT 5 ASSUMED)

Hex	Address		Explanation
	Hex	Decimal	
\$9280	37504		BEGINNING OF PROGRAM
9289	37513		SET HIGH BYTE, START OF CLEARED AREA
928D	37517		SET LOW BYTE, START OF CLEARED AREA
9291	37521		BYTE TO FILL MEMORY WITH
929C	37532		PAGE NUMBER FOR END OF CLEARED AREA
			—DON'T CLEAR BEYOND THIS (PAGE 146 MAXIMUM)
			—PAGE 146 (\$92) MEANS \$91FF IS LAST LOCATION THAT WILL BE CLEARED
92A5	37541		LAST BYTE OF PROGRAM

NOTE: \$8800-\$91FF ARE SET ASIDE FOR ADC, DAC, DATA STORAGE
\$9200-\$93FF ARE SET ASIDE FOR DAC, CLEAR MEMORY AND ADC
ASSEMBLY LANGUAGE PROGRAMS

is latched so it can be read out from ORA. The sample is stored and a delay subroutine is called. The program determines if allotted memory is full; if it isn't, it sends a Read high for another conversion.

Operation of the D/A converter under the listing given in Table IV proceeds as in the BASIC listing in Program 7. Port A DDRA is set for output. A high on CA2 triggers a scope connected to J6 and, after inversion by IC4, pulls low the D/A converter's Chip Enable line. A byte is then fetched from memory and sent to the D/A converter via ORA. The program then checks whether or not the memory specified has been scanned; if it hasn't, another byte is sent to ORA. After completing a set number of scans, the program returns to the routine that called it.

Table IV can be used to clear a specific block of memory before filling it with data from the A/D converter, or before storing the output from the D/A converter. Although memory clearing can be performed from BASIC, it's too slow for more than a 1K-byte block of memory used for repeated measurements.

Operation Under BASIC. The various assembly-language programs presented in this article are best used as subroutines called from a BASIC driver program. It's easy to set memory limits and data rates and change to the alternate port by POKEing new values into the assembly-language code. This permits use of the fast assembly-language routines without having to be familiar with assembly-language programming. The BASIC listings for Apple DAC, Apple ADC, and Clear Memory contain the three assembly-language programs discussed. Tables VI, VII, and VIII list the POKE values required to tailor the routines to your purposes.

These programs all assume you're using an Apple II Plus computer with 48K of user RAM and slot 5 in the computer. The memory map in Table IX reveals where everything is stored. If you're using a disk drive, you can keep the DOS from overwriting the machine-language program by booting the DOS, setting HIMEM:34815 and then loading the BASIC program. This protects operation by putting data storage and machine language above BASIC and below the DOS. Memory locations 34816 through 37375 are for data storage; 37376 through 37721 for the D/A, Clear, and A/D; and 37722 through 38399 for data or expansion.

The three assembly-language routines can be easily relocated, since

except Apple ADC, they contain no absolute addresses. Because delay routine MSEC calls \$9326 (memory location 37670) and \$9327 (location 37671), Table III must be changed to fit the new location. If slot 5 in the computer isn't used, the correct VIA address for the slot must be POKEd.

Capturing Waveforms. The Waveform Program combines D/A, A/D, and Clear routines and illustrates use of the VIA and Data Converter. The purpose here is to capture an audio waveform and display it on the CRT screen of an oscilloscope.

Load the Waveform Program, connect a microphone to *J1* and a scope to *J2*, and set *S2* to AC. Sing a steady "o-o-o-h-h-h" tone into the mic and set the

GAIN switch for a peak-to-peak signal level of less than 9 volts. Connect a lead from TRIG *J6* to the scope's trigger input and adjust the scope for a triggering. RUN the program while holding a note.

The computer will capture and display 1280 samples of the waveform. Since these samples are stored in memory, they can be SAVED on disk, written to a printer, or plotted on a strip chart, or the waveform could be Fourier analyzed if desired.

With some minor changes in the BASIC program, 256 samples of each of 10 different waveforms could be captured and selectively analyzed. Alternatively, they could be plotted in HIRES with about a 25% loss in vertical resolution, on 192 vertical points for 256 from the A/D converter. \diamond

TABLE IX—APPLE DATA CONVERTER MEMORY MAP

HEX		DECIMAL
\$FFFF	APPLE USES	65535
\$C100		49408
\$C0FF	PERIPHERAL CARD I/O SPACE FOR	49407
\$C080	6522 VIA (8 SLOTS)	49280
	APPLE USES	
\$BFFF	DOS	49151
\$9600		38400
\$95FF	SPACE FOR MACHINE LANGUAGE	38399
\$935A	PROGRAMS (MLP) OR CONVERTER DATA	37722
\$9359	ADC MLP	37721
\$9300		37632
	80 BYTES FOR MLP	
\$92A5	CLEAR MEMORY MLP	37541
\$9280		37504
	40 BYTES FOR MLP	
\$9257	DAC MLP	37463
\$9200		37376
\$91FF	ADC/DAC DATA STORAGE	37375
\$8800	(PAGES 136-145)	34816
\$87FF	FOR BASIC PROGRAMS	34815
\$6000	(SET HIMEM:34815)	24576
\$5FFF	HIGH RESOLUTION GRAPHICS	24575
\$2000		8192
\$1FFF		8191
\$0C00	FOR BASIC PROGRAMS	3072
\$0BFF	APPLE USES	3071
\$0000		0